

MECHANICAL CASE OUTLINE

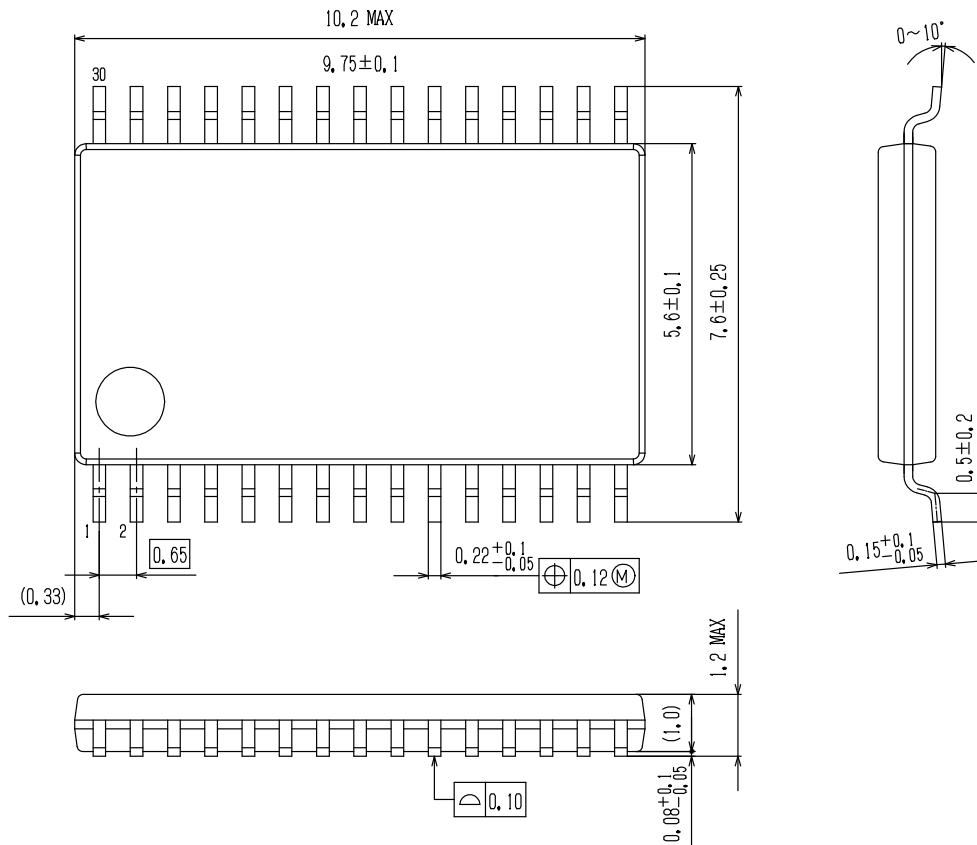
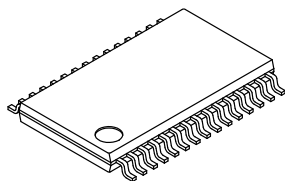
PACKAGE DIMENSIONS

ON Semiconductor®

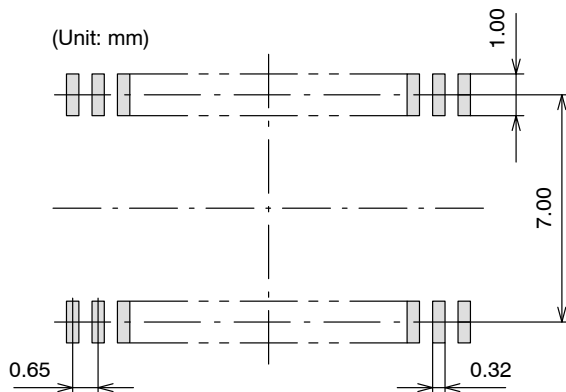


TSSOP30 5.6x9.75 / TSSOP30 (275 mil) CASE 948BB ISSUE A

DATE 31 OCT 2013



SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TSSOP30 5.6X9.75 / TSSOP30 (275 MIL)	PAGE 1 OF 2

